This listing of claims will replace all prior versions, and listings, of claims in the application:

## Listing of Claims:

- 1 1. (currently amended): A magnetic head comprising:
- 2 a substrate;
- a read head being fabricated upon said substrate;
- 4 a P1 pole being fabricated upon said read head;
- 5 a write gap layer being fabricated upon said P1 pole;
- a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole
- 7 tip includes a first sidewall portion being comprised of a seed layer material and a second
- 8 <u>sidewall</u> portion being comprised of electroplated a non-seed layer material, and wherein said P2
- 9 pole tip has a thickness dimension t, and a base having a width dimension W;
- and wherein said seed layer is comprised of an integrally formed layer of seed layer
- 11 material that forms said base of said P2 pole tip and said first sidewall portion of said P2 pole tip
- 12 that extends throughout said thickness t of said P2 pole tip.
- 1 2. (currently amended): A magnetic head as described in claim 1 wherein said electroplated
- 2 <u>non-seed layer</u> material that comprises said second <u>sidewall</u> portion of said P2 pole tip <u>is plated</u>
- 3 <u>disposed</u> upon said seed layer material that forms said first sidewall <u>portion</u> of said P2 pole tip.
- 1 3. (currently amended): A magnetic head as described in claim 1 wherein said seed layer
- 2 material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said
- 3 electroplated non-seed layer material is formed with a thickness of approximately 100 Å to
- 4 approximately 5000 Å.

- 1 4. (currently amended): A magnetic head as described in claim 3 wherein said seed layer
- 2 material thickness is approximately 250 Å and said electroplated non-seed layer material
- 3 thickness is approximately 1500 Å.
- 1 5. (currently amended): A magnetic head as described in claim 3 wherein said seed layer
- 2 material is comprised of <u>deposited</u> NiFe and said <u>electroplated</u> <u>non-seed layer</u> material is
- 3 comprised of electroplated NiFe.
- 1 6. (currently amended): A hard disk drive comprising:
- 2 at least one hard disk being fabricated for rotary motion upon a disk drive;
- 3 at least one magnetic head adapted to fly over said hard disk for writing data on said hard
- 4 disk, said magnetic head including:
- 5 a substrate;
- 6 a read head being fabricated upon said substrate;
- 7 a P1 pole being fabricated upon said read head;
- 8 a write gap layer being fabricated upon said P1 pole:
- 9 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole
- 10 tip includes a first sidewall portion being comprised of a seed layer and a second sidewall portion
- being comprised of electroplated a non-seed layer material, and wherein said P2 pole tip has a
- 12 thickness dimension t, and a base having a width dimension W;

- and wherein said seed layer is comprised of an integrally formed layer of seed layer
- 14 material that forms said base of said P2 pole tip and said first sidewall portion of said P2 pole tip
- that extends throughout said thickness t of said P2 pole tip.
- 1 7. (currently amended): A hard disk drive as described in claim 6 wherein said electroplated
- 2 <u>non-seed layer</u> material that comprises said second <u>sidewall</u> portion of said P2 pole tip <u>is-plated</u>
- 3 <u>disposed</u> upon said seed layer material that forms said first sidewall <u>portion</u> of said P2 pole tip.
- 1 8. (currently amended): A hard disk drive as described in claim 6 wherein said seed layer
- 2 material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said
- 3 electroplated non-seed layer material is formed with a thickness of approximately 100 Å to
- 4 approximately 5000 Å.
- 1 9. (currently amended): A hard disk drive as described in claim 8 wherein said seed layer
- 2 material thickness is approximately 250 Å and said electroplated non-seed layer material
- 3 thickness is approximately 1500 Å.
- 1 10. (currently amended): A hard disk drive as described in claim 8 wherein said seed layer
- 2 material is comprised of deposited NiFe and said electroplated non-seed layer material is
- 3 comprised of <u>electroplated</u> NiFe.

11-18 (withdrawn)

- 1 19. (currently amended): A magnetic head comprising:
- 2 a substrate;
- a read head being fabricated upon said substrate;
- 4 a P1 pole being fabricated upon said read head;
- 5 a write gap layer being fabricated upon said P1 pole;
- a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole
- 7 tip includes a base surface <u>layer</u> that is disposed upon said write gap layer and a <u>first</u> sidewall
- 8 surface <u>layer</u> that is disposed generally perpendicularly to said base surface <u>layer</u>, and wherein
- 9 said base surface <u>layer</u> and said first sidewall surface <u>layer</u> are comprised of an integrally formed
- 10 layer of P2 pole tip seed layer material;
- and wherein said P2 pole tip includes an electroplated a non-seed layer material portion,
- and wherein said P2 pole tip includes a second sidewall surface layer that is disposed opposite to
- said first sidewall surface <u>layer</u>, and wherein said second sidewall surface <u>layer</u> is comprised of
- 14 said electroplated non-seed layer material.
- 1 20. (currently amended): A magnetic head as described in claim 19 wherein said base
- 2 surface layer defines a width W of said P2 pole tip and said first sidewall layer defines a
- 3 thickness t of said P2 pole tip.
- 1 21. (currently amended): A magnetic head as described in claim 20, wherein said
- 2 electroplated non-seed layer material portion is plated disposed in part upon said first sidewall
- 3 surface seed layer material.

- 1 22. (currently amended): A magnetic head as described in claim 21 wherein said seed layer
- 2 material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said
- 3 electroplated non-seed layer material is formed with a thickness of approximately 100 Å to
- 4 approximately 5000 Å.
- 1 23. (currently amended): A magnetic head as described in claim 21 wherein said seed layer
- 2 material thickness is approximately 250 Å and said electroplated non-seed layer material
- 3 thickness is approximately 1500 Å.
- 1 24. (currently amended): A magnetic head as described in claim 21 wherein said seed layer
- 2 material is comprised of deposited NiFe and said electroplated non-seed layer material is
- 3 comprised of <u>electroplated</u> NiFe.